CERMET PLATINUM PALLADIUM SILVER CONDUCTOR 9564

ESL 9564 is a non-migrating platinum, palladium, silver conductor, excellent for use in multilayer hybrid circuits. ESL 9564 exhibits good adhesion, solderability, and leach resistance and it is compatible with a number of ESL dielectric and resistor systems.

PASTE DATA

RHEOLOGY: Thixotropic, screen printable paste

VISCOSITY:
(Brookfield RVT, ABZ Spindle, 10 rpm, 25.5°C±0.5°C) 250±25 Pa·s

BONDING MECHANISM: Mixed

SHELF LIFE: (25°C) 6 months

PROCESSING

SCREEN MESH/EMULSION: 325/25 μm

LEVELING TIME: (25°C) 5-10 minutes

DRYING AT 125°C: 10-15 minutes

FIRING RANGE: 850°C-930°C

OPTIMUM: 850°C

TIME AT PEAK: 10-12 minutes

RATE OF ASCENT/DESCENT: 60°C-100°C/minute

SUBSTRATE OF CALIBRATION: 96% alumina

THINNER: ESL 401

TYPICAL PROPERTIES

FIRED THICKNESS: 12.5±2.5 μm
**CAUTION:**
Proper industrial safety precautions should be exercised in using these products. Use with adequate ventilation. Avoid prolonged contact with skin or inhalation of any vapors emitted during use or heating of these compositions. The use of safety eye goggles, gloves or hand protection creams is recommended. Wash hands or skin thoroughly with soap and water after using these products. Do not eat or smoke in areas where these materials are used. Refer to appropriate MSDS sheet.

**DISCLAIMER:**
The product information and recommendations contained herein are based on data obtained by tests we believe to be accurate, but the accuracy and completeness thereof is not guaranteed. No warranty is expressed or implied regarding the accuracy of these data, the results obtained from the use hereof, or that any such use will not infringe any patent. Electro-Science assumes no liability for any injury, loss, or damage, direct or consequential arising out of its use by others. This information is furnished upon the condition that the person receiving it shall make their own tests to determine the suitability thereof for their particular use, before using it. User assumes all risk and liability whatsoever in connection with their intended use. Electro-Science’s only obligation shall be to replace such quantity of the product proved defective.

**APPROXIMATE COVERAGE:**
55-65 cm²/g

**RESISTIVITY:**
25-35 mΩ/sq.

**PRINTING RESOLUTION:** (Line/Space)
150 μm x 150 μm

**SOLDER WETTABILITY:**
(RMA flux, 5 sec. dip)
- 62 Sn/36 Pb/2 Ag (220°C±5°C) very good
- 63 Sn/37 Pb (250°C±5°C) good

**SOLDER LEACH:** (62 Sn/36 Pb/2 Ag, 220°C±5°C)
(No. of 10 sec. dip to double resistance of 0.25 mm wide x 100 mm long conductor) 5-7

**ADHESION:**
(90° pull, 2.0 mm x 2.0 mm pads, 62 Sn/36 Pb/2 Ag)
- Initial pull strength: 35-60 N
- Aged; 48 hours at 150°C: 25-45 N